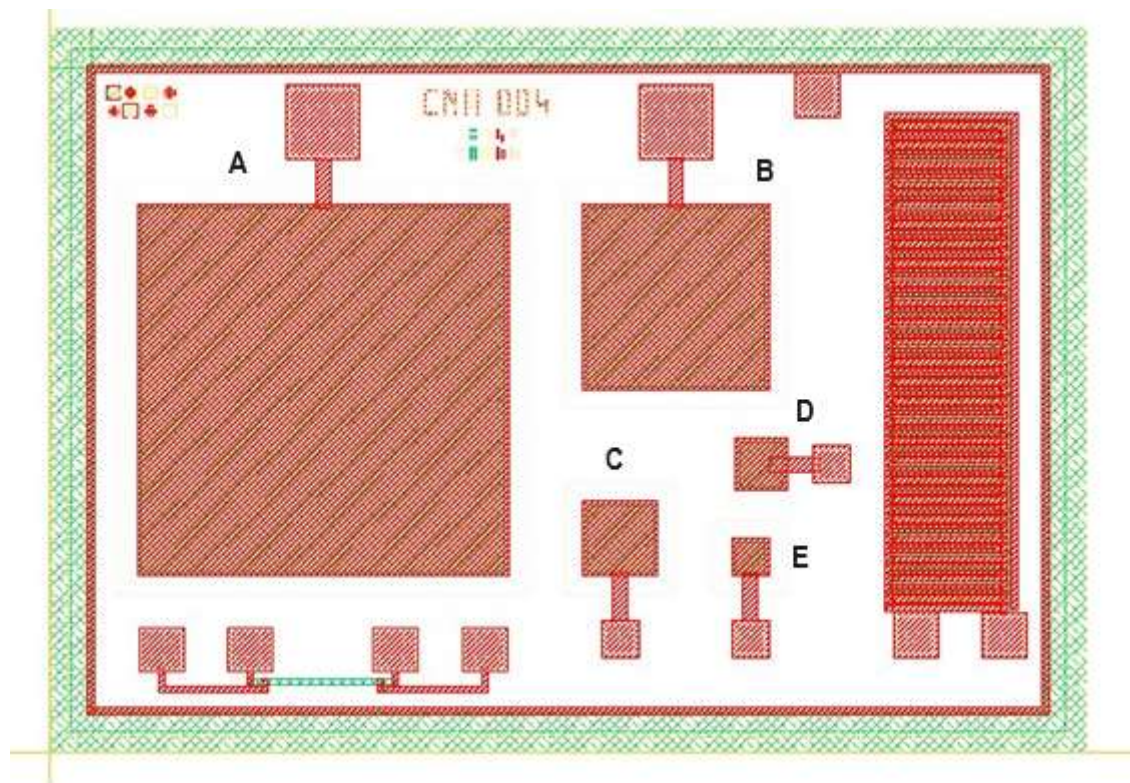


ANNEX I. Formulas

Value	Description	Units
C_{max}	Maximum capacity, obtained as an average of the last five values of the curve in accumulation situation, equivalent to the capacity of the oxide (C _{ox}).	pF
C_{min}	Minimum capacity, obtained as the minimum value of the curve.	pF
D_{ox}	Oxide thickness. $d_{ox} = \frac{\varepsilon_0 \cdot \varepsilon_{ox} \cdot S}{C_{max}}$	Å
N_a	Substrate doping. $\ln\left(\frac{Na}{n_i}\right) - \frac{q^2 \cdot n_i \cdot W_m^2}{4 \cdot \varepsilon_S \cdot k \cdot T} \left(\frac{Na}{n_i}\right) = 0$ $W_m = \varepsilon_S \cdot \left(\frac{1}{C_{min}^{HF}} - \frac{1}{C_{max}} \right)$	cm ⁻³
V_{FB}	Flat band voltage is the voltage for which the capacity is equal to the capacity of flat band (C _{FB}). $C_{FB} = \frac{1}{\frac{1}{C_{ox}} + \frac{1}{C_{SFB}}} \quad C_{SFB} = \sqrt{\frac{q^2 \cdot \varepsilon_S \cdot N_A}{k \cdot T}}$	V
N_{ss}	Total charge density on the insulator. $N_{ss} = (\Phi_{MS} - V_{FB}) \cdot \frac{C_{ox}}{q \cdot S}$	cm ⁻²
R_s	Serial resistance. $R_s = \frac{G_{acc}}{G_{acc}^2 + w^2 \cdot C_{acc}^2}$ <p>G_{acc}, C_{acc} = Accumulation conductance and capacitance</p> <p>Then the measured capacitance (C_m) and the measured conductance (G_m) are compensated for this obtained value of R_s according to the following equations:</p> $C_c = \frac{(G_m^2 + w^2 \cdot C_m^2) \cdot C_m}{a^2 + w^2 \cdot C_m^2} \quad G_c = \frac{(G_m^2 + w^2 \cdot C_m^2) \cdot a}{a^2 + w^2 \cdot C_m^2}$ $a = G_m - (G_m^2 + w^2 \cdot C_m^2) \cdot R_s$	Ω

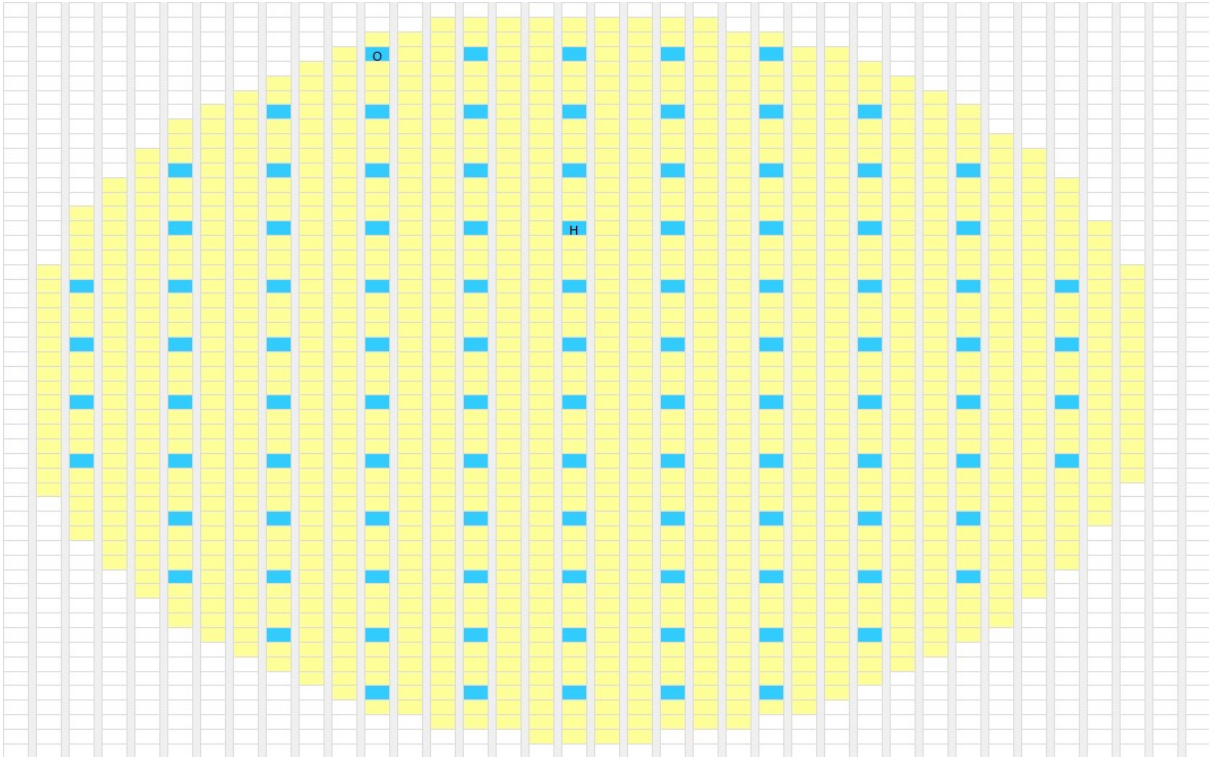
ANNEX II. Layout information CNM004



Layout capacitance chip
Chip overall dimensions are X=2790 μm , Y=1950 μm .

CAP	Area (μm^2)
A	980x980
B	480x480
C	180x180
D	120x120
E	80x80

ANNEX III. Wafermap file



Wafermap used in cartography
Total of 104 capacitances